

HVC359

Variable Capacitance Diode for VCO

REJ03G0489-0300

(Previous: ADE-208-419B)

Rev.3.00 Jan 17, 2005

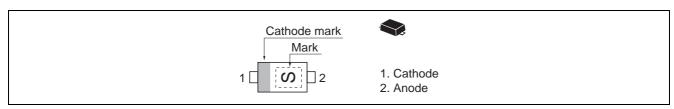
Features

- High capacitance ratio and good C-V linearity.
- To be usable at low voltage.
- Ultra small Flat Lead Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC359	S	UFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

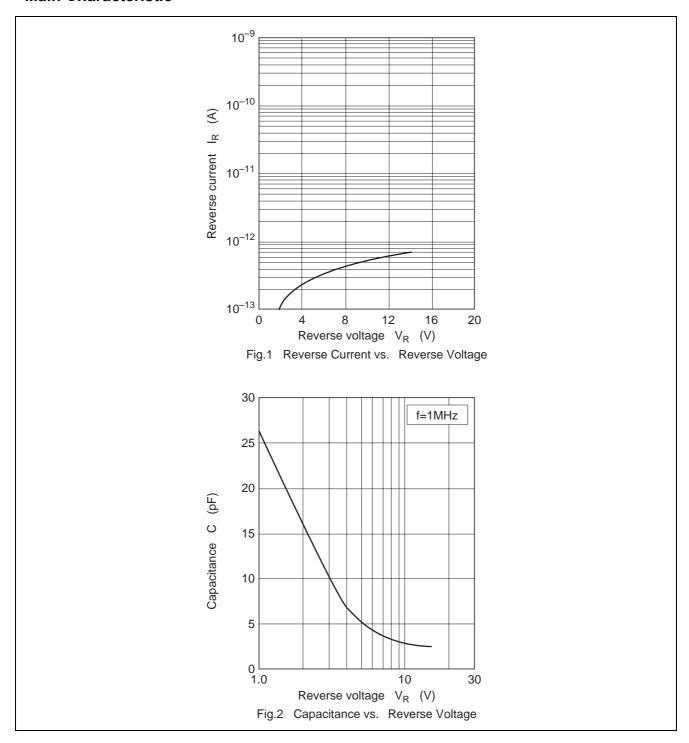
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

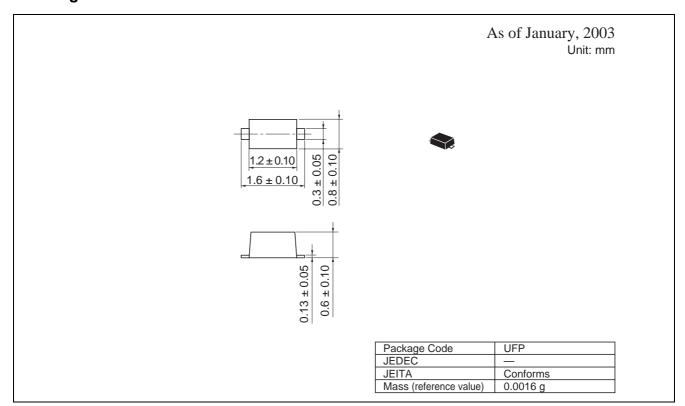
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 10 V
	I _{R2}	_	_	100		V _R = 10 V, Ta = 60°C
Capacitance	C ₁	24.8	_	29.8	pF	V _R = 1 V, f = 1 MHz
	C ₄	6.0	_	8.30		V _R = 4 V, f = 1 MHz
Capacitance ratio	n	3.00	_	_	_	C ₁ /C ₄
Series resistance	rs	_	_	1.50	Ω	V _R = 4 V, f = 100 MHz
ESD-Capability *1	_	200	_	_	V	C = 200 pF, R = 0 Ω , Both forward
						and reverse direction 1 pulse.

Note: 1. Failure criterion; $I_R \ge 20$ nA at $V_R = 10$ V

Main Characteristic



Package Dimensions



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